

ABSTRACT OF THE DISCLOSURE

A semiconductor polishing composition is disclosed. The composition includes fumed silica. The semiconductor polishing composition is an aqueous dispersion solution of fumed silica. Further, the number of particles of fumed silica having a particle diameter of 0.5 μm or more is 600,000 pieces/ml or less and the number of particles of fumed silica having a particle diameter of 1 μm or more is 6000 pieces/ml or less.